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DERWENT-WEEK: 200317

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TITLE: Apparatus and method for baking
wafer

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PATENT-FAMILY:

PUB-NO	PAGES	PUB-DATE	MAIN-IPC
KR 2002062437 A		July 26, 2002	N/A
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APPLICATION-DATA:

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KR2002062437A	N/A	
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ABSTRACTED-PUB-NO: KR2002062437A

BASIC-ABSTRACT:

NOVELTY - An apparatus for baking a wafer is provided to prevent a process defect caused by a wafer inaccurately placed on a heating plate by making a detecting unit using a sensor and a lift pin detect the wafer placed on the heating plate, and to prevent recurrence of a defect by readjusting a loading position of a robot.

DETAILED DESCRIPTION - A wafer to bake is placed on the heating plate(110).

The lift pin loads/unloads the wafer to/from the heating plate, installed in the heating plate. A guide pin guides the wafer loaded to the heating plate, installed at the edge of the heating plate. A wafer detecting unit detects the wafer inaccurately loaded to the heating plate, installed in the guide pin.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: APPARATUS METHOD BAKE WAFER

DERWENT-CLASS: U11

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